

Gallium Nitride 28V, 5W, DC-1500MHz MMIC PA

Built using the SIGANTIC[®] NRF1 process - A proprietary GaN-on-Silicon technology

FEATURES

- Optimized for broadband operation from DC-1500-MHz
- Input and output matched to 50 Ohms
- > 38dBm saturated power up to 1000MHz
- High small signal gain
 - 22dB @ 200MHz
 - 18dB @ 1000MHz
- Low noise figure
 - 1.8dB @ 200MHz
 - 2.5dB @ 1000MHz
- Subject to EAR99 export control



**4mm x 4mm
QFN Package
With Exposed Pad**



RF Specifications (CW, DC-1000MHz): $V_{DS} = 28V$, $I_{DQ} = 100mA$, $T_A = 25^{\circ}C$, Measured in Nitronex 50 Ohm test fixture.

Symbol	Parameter	Min	Typ	Max	Units
G_{SS}	Small-signal Gain	17.5	19.0	-	dB
P_{SAT}	Saturated Output Power	36.5	38	-	dBm
G_P	Gain at P_{SAT}	13	14.5	-	dB
η	Drain Efficiency at P_{SAT}	35	45	-	%
	Gain Flatness at P_{SAT}	-	+/- 3.5	-	dB
	Harmonics at $P_{OUT} = 36dBm$	-	-20	-	dBc
NF	Noise Figure	-	2.5		
OIP3	Output IP3, 1MHz spacing, 32dBm/tone	-	47	-	dBm
IRL	Input Return Loss	-	-8	-	dB
ORL	Output Return Loss	-	-15	-	dB

NPA1003 Preliminary Datasheet



DC Specifications: $T_C = 25^\circ\text{C}$

Symbol	Parameter	Min	Typ	Max	Units
Off Characteristics					
V_{BDS}	Drain-Source Breakdown Voltage ($V_{GS} = -8\text{V}$, $I_D = 2\text{mA}$)	100	-	-	V
I_{DLK}	Drain-Source Leakage Current ($V_{GS} = -8\text{V}$, $V_{DS} = 60\text{V}$)	-	0.5	1.0	mA
On Characteristics					
V_T	Gate Threshold Voltage ($V_{DS} = 28\text{V}$, $I_D = 2\text{mA}$)	-2.1	-1.6	-1.1	V
V_{GSQ}	Gate Quiescent Voltage ($V_{DS} = 28\text{V}$, $I_D = 100\text{mA}$)	-1.7	-1.2	-0.7	V
R_{ON}	On Resistance ($V_{GS} = 2\text{V}$, $I_D = 15\text{mA}$)	-	2.0	-	Ω
$I_{D,MAX}$	Drain Current ($V_{DS} = 7\text{V}$ pulsed, $300\mu\text{s}$ pulse width, 0.2% duty cycle, $V_{GS} = 2.0\text{V}$)	1.1	1.4	-	A

Thermal Resistance Specification

Symbol	Parameter	Min	Typ	Max	Units
θ_{JC}	Thermal Resistance (Junction-to-Case), $T_J = 180^\circ\text{C}$	-	12.0	-	$^\circ\text{C}/\text{W}$

Absolute Maximum Ratings: Not simultaneous, $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Max	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	-10 to 3	V
I_G	Gate Current	10	mA
P_T	Total Device Power Dissipation (Derated above 25°C)	14.5	W
T_{STG}	Storage Temperature Range	-65 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature	200	$^\circ\text{C}$
HBM	Human Body Model ESD Rating (per JESD22-A114)	TBD	
MM	Machine Model ESD Rating (per JESD22-A115)	TBD	
MSL	Moisture sensitivity level (per IPC/JEDEC J-STD-020)	TBD	
P_{IN}	Maximum Input Power	TBD	

RF Performance in 50 Ohm Test Fixture With External Bias Tee

$V_{DS} = 28V$, $I_{DQ} = 100mA$, $T_A = 25^\circ C$,

CW signal unless otherwise noted, Reference plane: Connectors

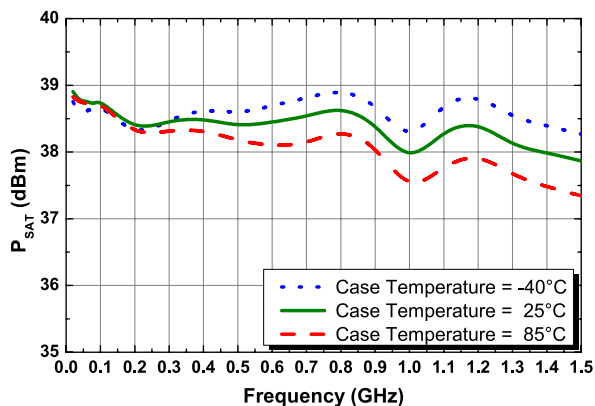


Figure 1 - Saturated Output Power vs Frequency

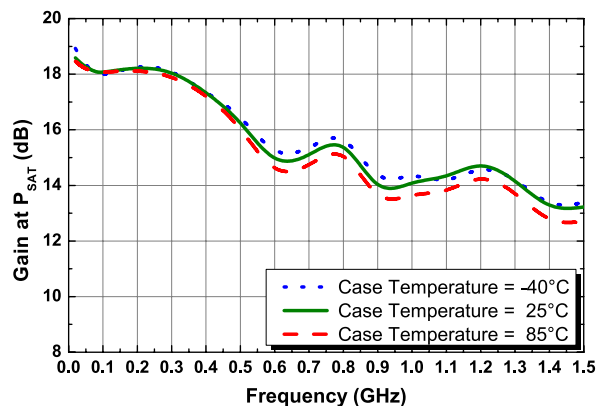


Figure 2 - Gain at Saturated Output Power vs Frequency

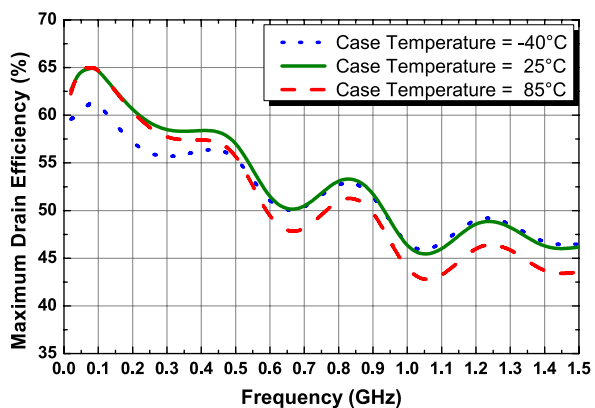


Figure 3 - Maximum Drain Efficiency vs Frequency

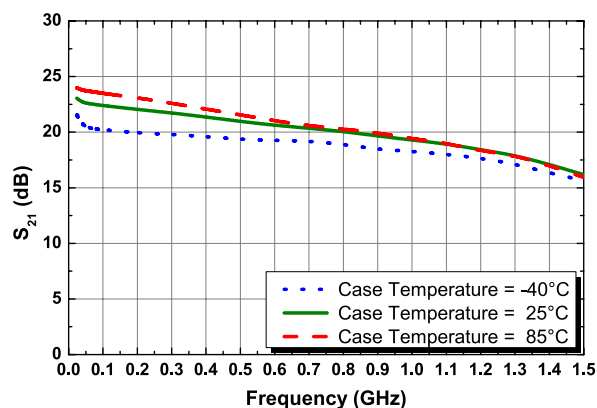


Figure 4 - Small-Signal Gain vs Frequency

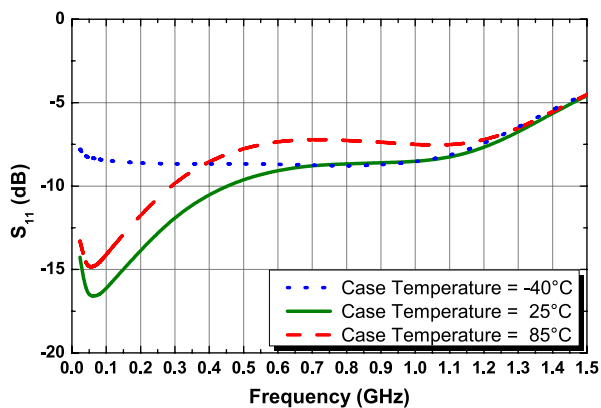


Figure 5 - Input Return Loss vs Frequency

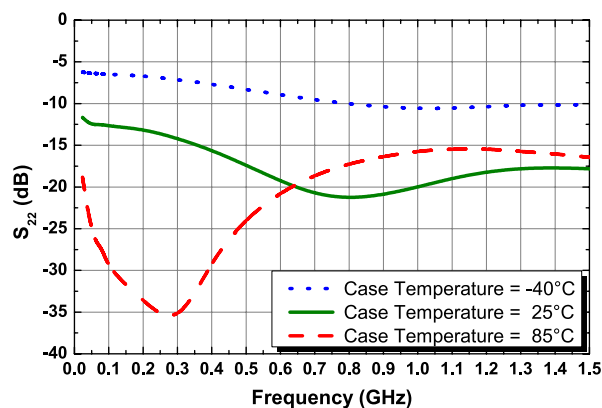


Figure 6 - Output Return Loss vs Frequency

RF Performance in 50 Ohm Test Fixture With External Bias Tee

$V_{DS} = 28V, I_{DQ} = 100mA, T_A = 25^\circ C,$

CW signal unless otherwise noted, Reference plane: Connectors

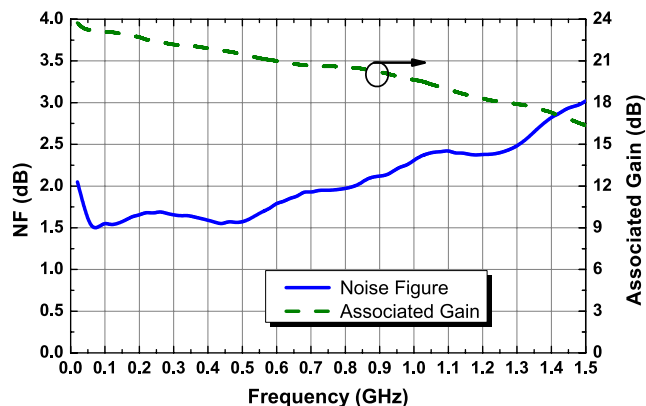


Figure 7 - Noise Figure vs Frequency

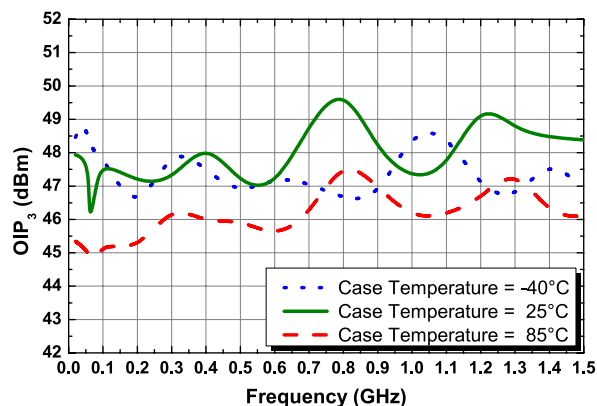


Figure 8 - Output IP₃ at P_{OUT} ~ 35dBm vs Frequency

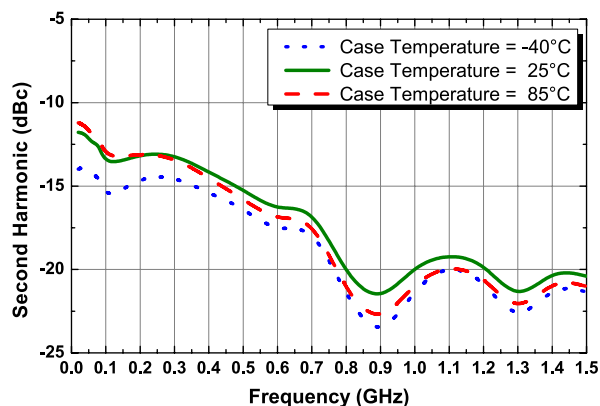


Figure 9 - Second Harmonic at P_{OUT} = 36dBm vs Frequency

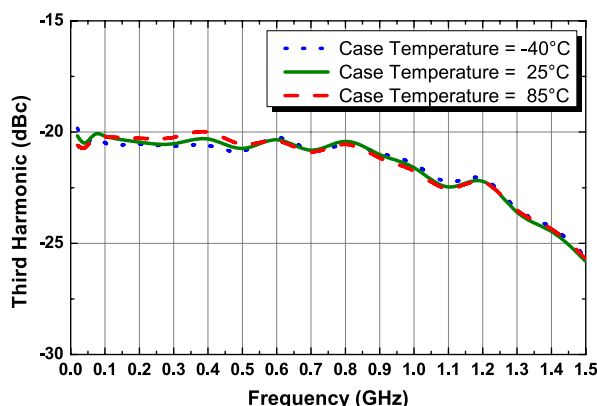


Figure 10 - Third Harmonic at P_{OUT} = 36dBm vs Frequency

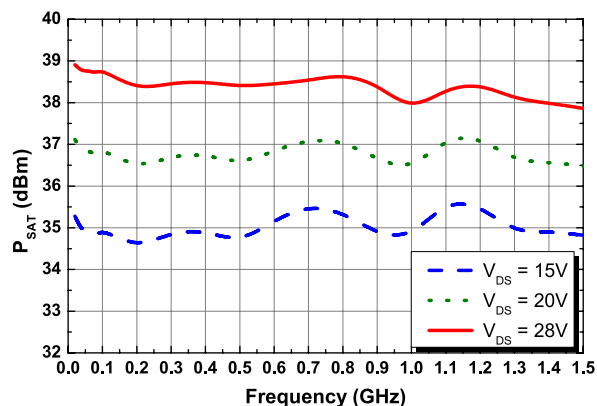


Figure 11 - Saturated Output Power vs V_{DS} and Frequency

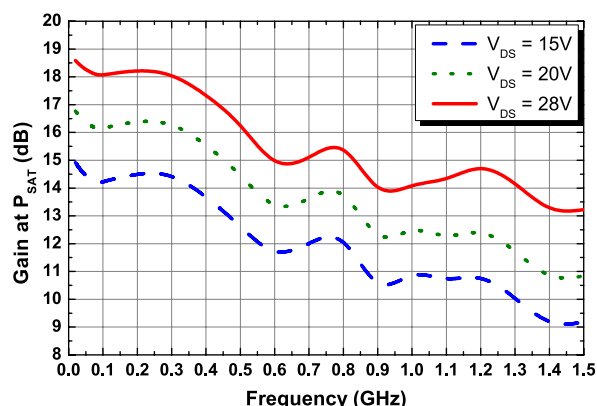


Figure 12 - Gain at Saturated Output Power vs V_{DS} and Frequency

RF Performance in 50 Ohm Test Fixture With External Bias Tee

$V_{DS} = 28V$, $I_{DQ} = 100mA$, $T_A = 25^\circ C$,

CW signal unless otherwise noted, Reference plane: Connectors

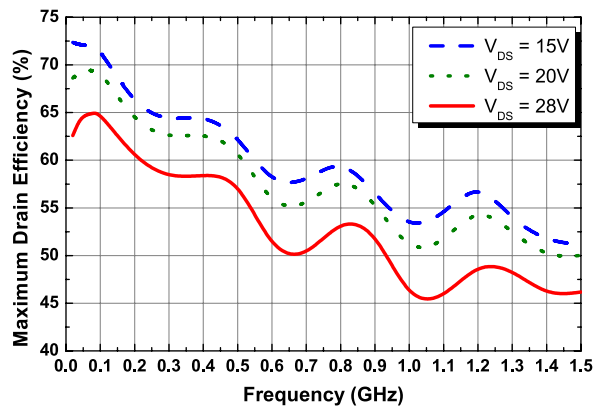


Figure 13 - Maximum Drain Efficiency vs V_{DS} and Frequency

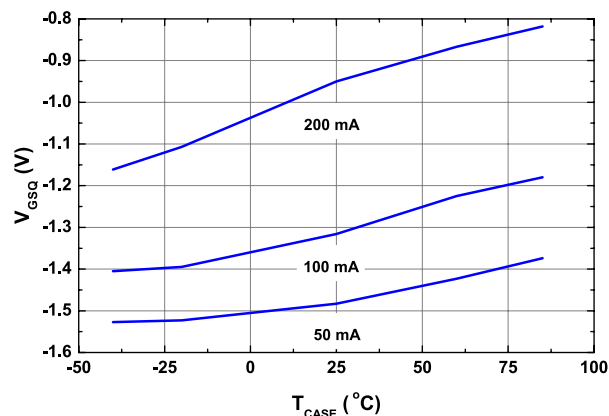


Figure 14 - Quiescent Gate Voltage (V_{GSQ}) Required to Reach I_{DQ} vs T_{CASE}

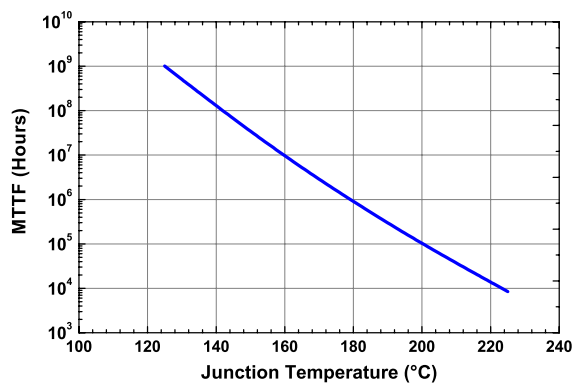


Figure 15 - MTTF of NRF1 Devices as a Function of Junction Temperature

NPA1003 Preliminary Datasheet

Ordering Information¹

Part Number	Order Multiple	Description
NPA1003QAT	92	Tube; NPA1003 in QA (4x4 QFN-16 lead with exposed pad) Package
NPA1003QAR	1500	Tape and Reel; NPA1003 in QA (4x4 QFN-16 lead with exposed pad) Package

1: To find a Nitronex contact in your area, visit our website at <http://www.nitronex.com>

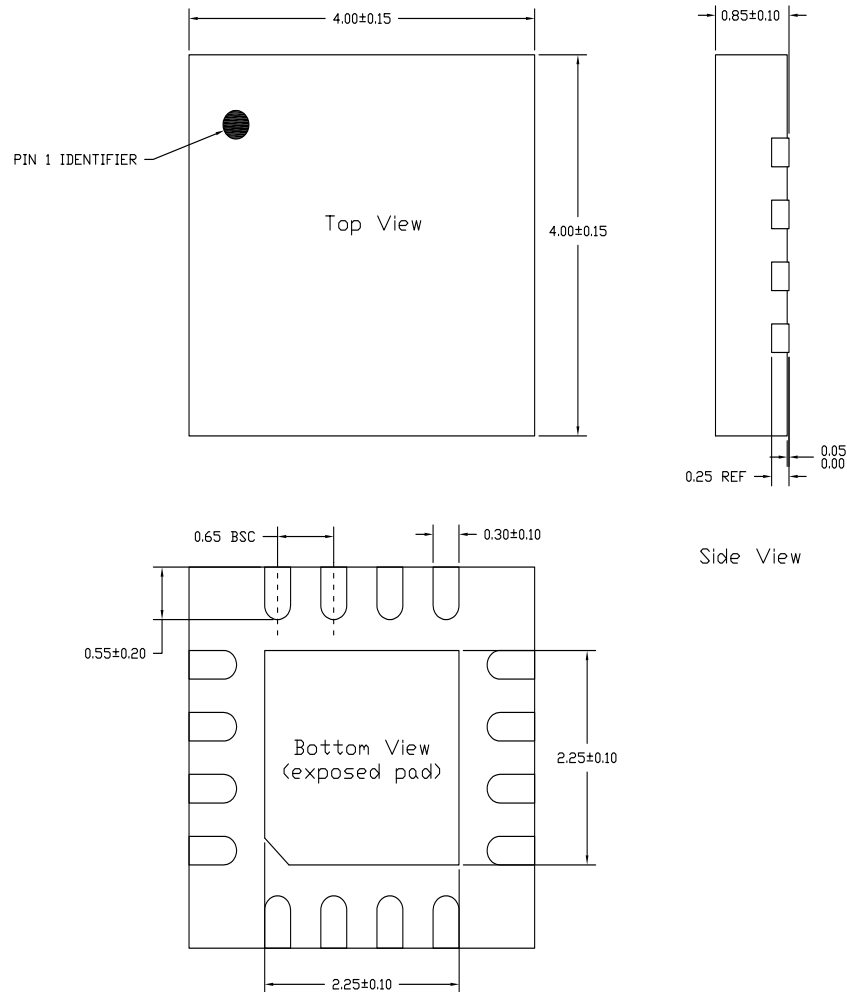


Figure 16 - QA Package Dimensions and Pinout (all dimensions are in millimeters)

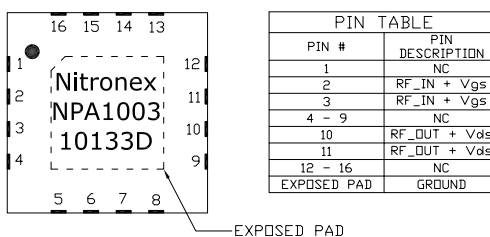


Figure 17 - Terminal Identification

NPA1003 Preliminary Datasheet



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Additional Information

**This part is lead-free and is compliant with the RoHS directive
(Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).**

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